

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WILLIAM S.H. CHEUNG	07/20/2014
RECEIVING PARTY DATA	
Name:	ADC TECH INTERNATIONAL LTD.
Street Address:	RM A02, 13/F UNION HING YIP FACTORY BLDG, NO.20
Internal Address:	HING YIP STREET, KWUN TONG KOWLOON
City:	KWUN TONG KOWLOON
State/Country:	HONG KONG
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15839176
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	ADC-012-US-DIV
NAME OF SUBMITTER:	MICHELE GREENBERG
SIGNATURE:	/mg/
DATE SIGNED:	12/12/2017
Total Attachments: 2	
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ASSIGNMENT & DECLARATION

WHEREAS, I, William S.H. CHEUNG (hereinafter the "Assignor"), residing Bellington Wayside Golders Green, London, NW118QY, United Kingdom, believe I am the original sole inventor of certain inventions or improvements claimed and/or disclosed in an application for Letters Patent which I have made, entitled SYSTEM AND METHOD FOR ELECTRET SURFACE POTENTIAL RESTORATION BY A DIRECTIONAL PULSATING ELECTRIC FIELD, filed concurrently herewith; and

WHEREAS, the above-identified application was made or authorized to be made by me.

WHEREAS, I hereby acknowledge that any willful false statement made in this Assignment & Declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

WHEREAS, ADC Tech International Ltd. (hereinafter the "Assignee"), of RM A02, 13/F Union Hing Yip Factory Bldg, No.20, Hing Yip Street, Kwun Tong Kowloon, Hong Kong, is desirous of acquiring the entire right, title and interest in and to the said inventions or improvements and in and to the said applications, and in, to and under any and all Letters Patent which may be granted on or as a result thereof in any and all countries, including the right to file, prosecute and otherwise pursue said applications, in the name of Assignee as Applicant, and to said inventions or improvements in any and all jurisdictions.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I, said Assignor, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over to said Assignee, the entire right, title and interest in and to said invention or improvement and said application and any and all continuations, divisionals, non-provisionals, and renewals of and substitutes for said applications, and in, to and under any and all Letters Patent which may be granted on or as a result thereof in the United States and any and all other countries, and any reissue or reissues or extension or extensions of said Letters Patent, and assign to and authorize said Assignee, to file prosecute and otherwise pursue, in the name of Assignee as Applicant, applications for Letters Patent in all countries, the same to be held and enjoyed by said Assignee, its successors, assigns, nominees or legal representatives, to the full end of the term or terms for which said Letters Patent, respectively, may be granted, reissued or extended, as fully and entirely as the same would have been held and enjoyed by me had this assignment, sale and transfer not been made.

AND I hereby covenant that I have full right to convey the entire interest herein assigned and that I have not executed and will not execute any agreement in conflict herewith, and I further covenant and agree that I will each time request is made and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said inventions or improvements, said applications and said Letters Patent to said Assignee, its successors, assigns, nominees, or legal representatives, and I agree to communicate to said Assignee or to its nominees all known facts respecting said inventions or improvements, said applications and said Letters Patent, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisional, continuing, reissue and foreign applications, to make all

rightful oaths, and generally to do everything possible to aid said Assignee, its successors, assigns, nominees and legal representatives to obtain and enforce for its or their own benefit proper patent protection for said inventions or improvements in any and all countries, all such actions to be at the sole expense of Assignee.

AND, I hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any country or countries foreign to the United States whose duty it is to issue patents on applications as aforesaid, to issue to said assignee, as assignee of the entire right, title and interest, any and all Letters Patent for said inventions or improvements, including any and all Letters Patent of the United States which may be issued and granted on or as a result of the application aforesaid, in accordance with the terms of the assignment.

IN WITNESS WHEREOF, I have hereunto set my hand and seal.

20/07/2014
Date

William S.H. Cheung
William S.H. CHEUNG
Inventor